Features

- Fast Read Access Time 55 ns
- Low-power CMOS Operation
 - 100 µA Max Standby
 - 25 mA Max Active at 5 MHz
- JEDEC Standard Packages
 - 32-lead PDIP
 - 32-lead PLCC
 - 32-lead TSOP
- 5V \pm 10% Supply
- High-reliability CMOS Technology
 - 2,000V ESD Protection
 - 200 mA Latch-up Immunity
- Rapid Programming Algorithm 100 μs/Byte (Typical)
- CMOS- and TTL-compatible Inputs and Outputs
- Integrated Product Identification Code
- Industrial and Automotive Temperature Ranges
- Green (Pb/Halide-free) Packaging Option

1. Description

The AT27C020 is a low-power, high-performance, 2,097,152-bit, one-time program-mable read-only memory (OTP EPROM) organized as 256K by 8 bits. It requires only one 5V power supply in normal read mode operation. Any byte can be accessed in less than 55 ns, eliminating the need for speed-reducing WAIT states on high-performance microprocessor systems.

In read mode, the AT27C020 typically consumes 8 mA. Standby mode supply current is typically less than 10 μ A.

The AT27C020 is available in a choice of industry-standard JEDEC-approved one-time programmable (OTP) plastic PDIP, PLCC and TSOP packages. All devices feature two-line control ($\overline{\text{CE}}$, $\overline{\text{OE}}$) to give designers the flexibility to prevent bus contention.

With 256K bytes storage capability, the AT27C020 allows firmware to be stored reliably and to be accessed by the system without the delays of mass storage media.

Atmel's AT27C020 has additional features to ensure high quality and efficient production use. The Rapid Programming Algorithm reduces the time required to program the part and guarantees reliable programming. Programming time is typically only 100 µs/byte. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry-standard programming equipment to select the proper programming algorithms and voltages.



2-megabit (256K x 8) OTP EPROM

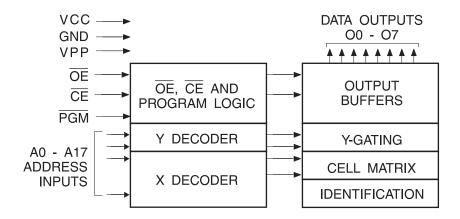
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3. System Considerations

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed datasheet limits, resulting in device non-conformance. At a minimum, a 0.1 μ F high-frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the V_{CC} and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply-voltage level on printed circuit boards with large EPROM arrays, a 4.7 μ F bulk electrolytic capacitor should be utilized, again connected between the V_{CC} and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

4. Block Diagram



5. Absolute Maximum Ratings*

Temperature under Bias	55°C to +125°C
Storage Temperature	65°C to +150°C
Voltage on Any Pin with Respect to Ground	2.0V to +7.0V ⁽¹⁾
Voltage on A9 with Respect to Ground	2.0V to +14.0V ⁽¹⁾
V _{PP} Supply Voltage with Respect to Ground	2.0V to +14.0V ⁽¹⁾

*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: 1. Minimum voltage is -0.6V DC, which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is $V_{CC} + 0.75V$ DC, which may overshoot to +7.0V for pulses of less than 20 ns.





Operating Modes

Mode/Pin	CE	ŌĒ	PGM	Ai	V _{PP}	Outputs
Read	V _{IL}	V _{IL}	X ⁽¹⁾	Ai	Х	D _{OUT}
Output Disable	X	V _{IH}	Х	X	Х	High-Z
Standby	V _{IH}	Х	Х	X	Х	High-Z
Rapid Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	V_{PP}	D _{IN}
PGM Verify	V_{IL}	V _{IL}	V _{IH}	Ai	V_{PP}	D _{OUT}
PGM Inhibit	V _{IH}	Х	Х	X	V_{PP}	High-Z
Product Identification ⁽⁴⁾	V _{IL}	V _{IL}	x	$A9 = V_H^{(3)}$ $A0 = V_{IH} \text{ or } V_{IL}$ $A1 - A17 = V_{IL}$	x	Identification Code

- Notes: 1. X can be V_{IL} or V_{IH} .
 - 2. Refer to Programming Characteristics.
 - 3. $V_H = 12.0 \pm 0.5V$.
 - 4. Two identifier bytes may be selected. All Ai inputs are held low (V_{IL}) except A9, which is set to V_H and A0, which is toggled low (V_{IL}) to select the Manufacturer's Identification byte and high (V_{IH}) to select the Device Code byte.

DC and AC Operating Conditions for Read Operation

		AT27	C020
		-55	-90
On exacting Terran exact up (Coop)	Ind.	-40° C - 85° C	-40° C - 85° C
Operating Temperature (Case)	Auto.		-40° C - 125° C
V _{CC} Power Supply		5V ± 10%	5V ± 10%

DC and Operating Characteristics for Read Operation

Symbol	Parameter	Condition	Min	Max	Units
ILI	Input Load Current	$V_{IN} = 0V$ to V_{CC} (Com., Ind.)		±1.0	μΑ
I _{LO}	Output Leakage Current	V _{OUT} = 0V to V _{CC} (Com., Ind.)		±5.0	μΑ
I _{PP} ⁽²⁾	V _{PP} ⁽¹⁾ Read/Standby Current	$V_{PP} = V_{CC}$		±10	μA
	V _{CC} ⁽¹⁾ Standby Current	I_{SB1} (CMOS), $\overline{CE} = V_{CC} \pm 0.3V$		100	μA
I _{SB}		I_{SB2} (TTL), \overline{CE} = 2.0 to V_{CC} + 0.5V		1.0	mA
I _{cc}	V _{CC} Active Current	$f = 5 \text{ MHz}, I_{OUT} = 0 \text{ mA}, \overline{CE} = V_{IL}$		25	mA
V _{IL}	Input Low Voltage		-0.6	0.8	V
V _{IH}	Input High Voltage		2.0	V _{CC} + 0.5	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		0.4	V
V _{OH}	Output High Voltage	I _{OH} = -400 μA	2.4		V

1. V_{CC} must be applied simultaneously or before V_{PP} , and removed simultaneously or after V_{PP} .

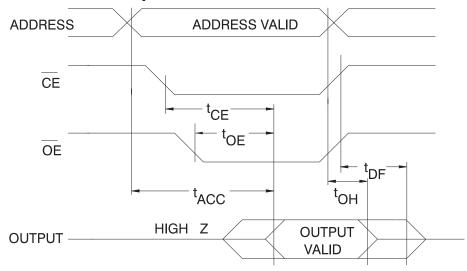
2. V_{PP} may be connected directly to V_{CC} except during programming. The supply current would then be the sum of I_{CC} and I_{PP} .

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9. AC Characteristics for Read Operation

				AT27			
				55	-90		
Symbol	Parameter	Condition	Min	Max	Min	Max	Units
t _{ACC} (3)	Address to Output Delay	CE = OE = V _{IL}		55		90	ns
t _{CE} ⁽²⁾	CE to Output Delay	OE = V _{IL}		55		90	ns
t _{OE} ⁽²⁾⁽³⁾	OE to Output Delay	CE = V _{IL}		20		35	ns
t _{DF} ⁽⁴⁾⁽⁵⁾	OE or CE High to Output Float, Whichever Occurred First			18		20	ns
t _{OH}	Output Hold from Address, $\overline{\text{CE}}$ or $\overline{\text{OE}}$, Whichever Occurred First		7		0		ns

10. AC Waveforms for Read Operation⁽¹⁾



Notes: 1. Timing measurement references are 0.8V and 2.0V. Input AC drive levels are 0.45V and 2.4V, unless otherwise specified.

- 2. $\overline{\text{OE}}$ may be delayed up to t_{CE} t_{OE} after the falling edge of $\overline{\text{CE}}$ without impact on t_{CE} .
- 3. $\overline{\text{OE}}$ may be delayed up to t_{ACC} t_{OE} after the address is valid without impact on t_{ACC} .
- 4. This parameter is only sampled and is not 100% tested.
- 5. Output float is defined as the point when data is no longer driven.





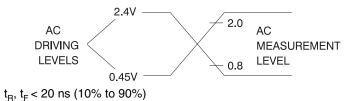
11. Input Test Waveforms and Measurement Levels

For -55 devices only:

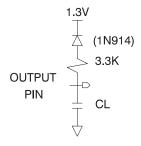


 t_R , t_F < 5 ns (10% to 90%)

For -90 devices only:



12. Output Test Load



Note: CL = 100 pF including jig capacitance except -55 devices, where CL = 30 pF.

13. Pin Capacitance

 $f = 1 \text{ MHz}, T = 25^{\circ} C^{(1)}$

Symbol	Тур	Max	Units	Conditions
C _{IN}	4	8	pF	$V_{IN} = 0V$
C _{OUT}	8	12	pF	V _{OUT} = 0V

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.



15. DC Programming Characteristics

 $T_A = 25 \pm 5^{\circ}C$, $V_{CC} = 6.5 \pm 0.25V$, $V_{PP} = 13.0 \pm 0.25V$

			Lir	Limits	
Symbol	Parameter	Test Conditions	Min	Max	Units
I _{LI}	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		±10	μΑ
V _{IL}	Input Low Level		-0.6	0.8	V
V _{IH}	Input High Level		2.0	V _{CC} + 1.0	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		0.4	V
V _{OH}	Output High Voltage	I _{OH} = -400 μA	2.4		V
I _{CC2}	V _{CC} Supply Current (Program and Verify)			40	mA
I _{PP2}	V _{PP} Supply Current	CE = PGM = V _{IL}		20	mA
V _{ID}	A9 Product Identification Voltage		11.5	12.5	V

16. AC Programming Characteristics

 $T_A = 25 \pm 5^{\circ}C, V_{CC} = 6.5 \pm 0.25V, V_{PP} = 13.0 \pm 0.25V$

			Lir	nits	
Symbol	Parameter	Test Condition (1)	Min	Max	Units
t _{AS}	Address Setup Time		2		μs
t_{CES}	CE Setup Time		2		μs
t _{OES}	OE Setup Time	Input Rise and Fall Times:	2		μs
t _{DS}	Data Setup Time	(10% to 90%) 20 ns	2		μs
t _{AH}	Address Hold Time	Input Pulse Levels:	0		μs
t _{DH}	Data Hold Time	0.45V to 2.4V	2		μs
t _{DFP}	OE High to Output Float Delay ⁽²⁾		0	130	ns
t _{VPS}	V _{PP} Setup Time	Input Timing Reference Level: 0.8V to 2.0V	2		μs
t _{VCS}	V _{CC} Setup Time	0.57 to 2.57	2		μs
t _{PW}	PGM Program Pulse Width ⁽³⁾	Output Timing Reference Level:	95	105	μs
t _{OE}	Data Valid from OE	0.8V to 2.0V		150	ns
t _{PRT}	V _{PP} Pulse Rise Time During Programming		50		ns

Notes: 1. V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after V_{PP} .

- 2. This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven see timing diagram.
- 3. Program Pulse width tolerance is 100 μ s \pm 5%.

17. Atmel's AT27C020 Integrated Product Identification Code

		Pins								
Codes	A0	07	06	O 5	04	О3	O2	01	00	Hex Data
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device Type	1	1	0	0	0	0	1	1	0	86

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19. Ordering Information

19.1 Standard Package

t _{ACC}	I _{CC} (mA)				
(ns)	Active	Standby	Ordering Code	Package	Operation Range
55	25	0.1	AT27C020-55JI AT27C020-55PI AT27C020-55TI	32J 32P6 32T	Industrial (-40° C to 85° C)
90	25	0.1	AT27C020-90JI AT27C020-90PI AT27C020-90TI	32J 32P6 32T	Industrial (-40° C to 85° C)
	25	0.1	AT27C020-90JA AT27C020-90PA	32J 32P6	Automotive (-40° C to 125° C)

Note: Not recommended for new designs. Use Green package option.

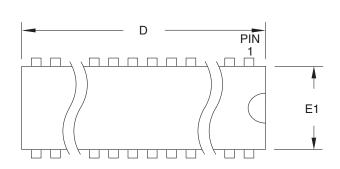
19.2 Green Package (Pb/Halide-free)

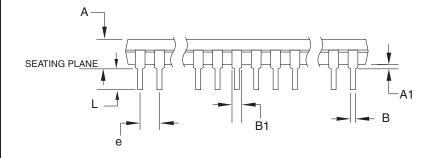
t _{ACC}	I _{CC} (mA)				
(ns)	Active	Standby	Ordering Code	Package	Operation Range
55	25	0.1	AT27C020-55JU AT27C020-55PU AT27C020-55TU	32J 32P6 32T	Industrial (-40° C to 85° C)
90	25	0.1	AT27C020-90JU AT27C020-90PU AT27C020-90TU	32J 32P6 32T	Industrial (-40° C to 85° C)

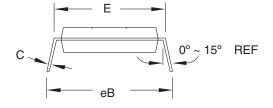
Package Type					
32-lead, Plastic J-leaded Chip Carrier (PLCC)					
32P6	32-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)				
32T	32-lead, Plastic Thin Small Outline Package (TSOP)				



20.2 32P6 - PDIP







Note: 1. Dimensions D and E1 do not include mold Flash or Protrusion.

Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
А	_	_	4.826	
A1	0.381	_	-	
D	41.783	_	42.291	Note 1
E	15.240	_	15.875	
E1	13.462	_	13.970	Note 1
В	0.356	_	0.559	
B1	1.041	_	1.651	
L	3.048	_	3.556	
С	0.203	_	0.381	
eB	15.494	_	17.526	
е	2.540 TYP			

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	32P6 , 32-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)	32P6	В